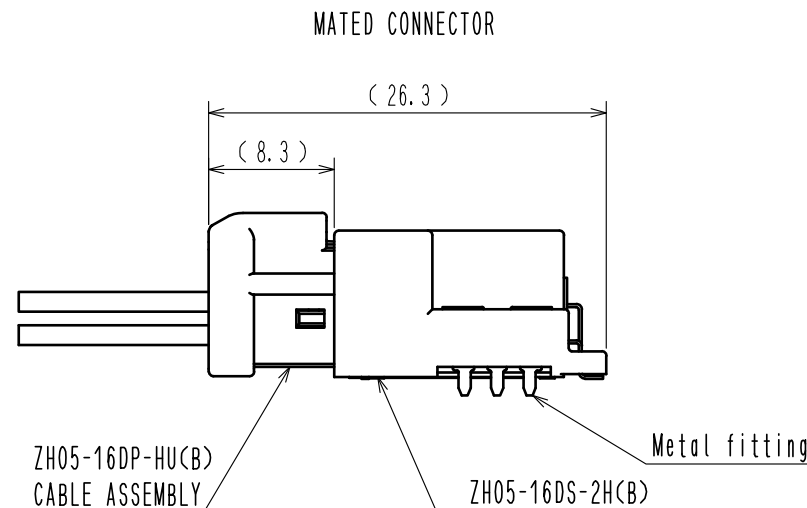
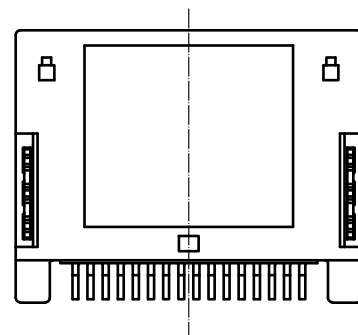
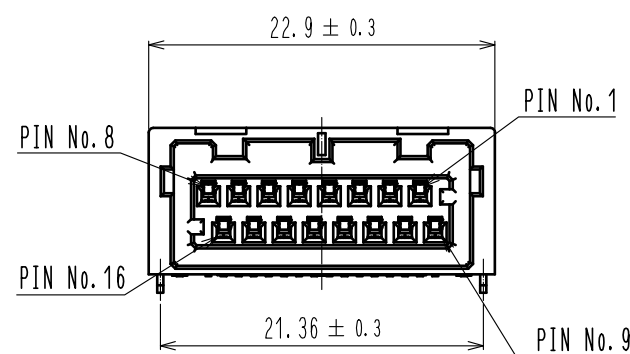
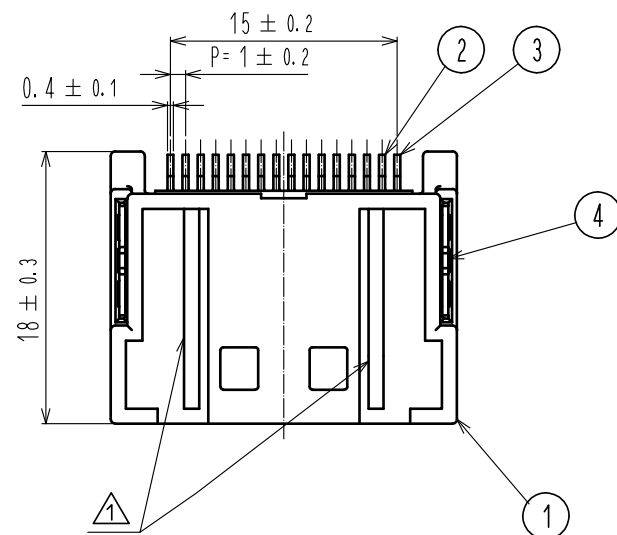
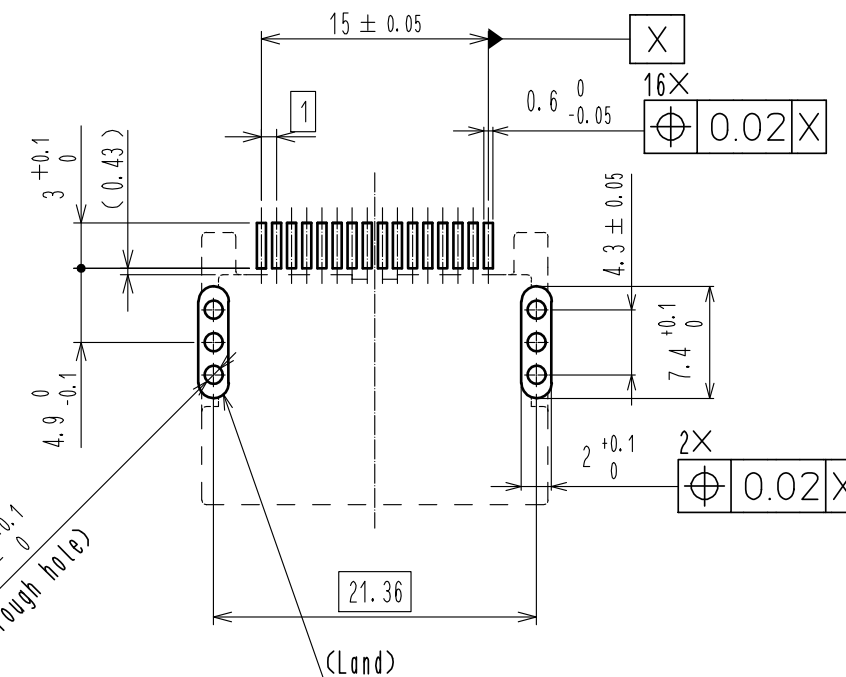


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In case of consideration for using Automotive equipment / device which demand high reliability, kindly contact our sales window correspondents.

ELV, RoHS COMPLIANT



RECOMMENDED PCB PATTERN (FREE)
(PCB THICKNESS: t=1.6mm. METAL MASK THICKNESS: t=0.1mm)



NOTE 1. RECOMMENDED TEMPERATURE PROFILE FOR REFLOW
(REFER TO RIGHT FIG.)
USED REFLOW SYSTEM

IR IN THE AIR OR NITROGEN
NO. OF CYCLES : 2 MAX
PEAK : 250°C
OVER 230°C : 20~40s
PREHEAT : 150~180°C
90~120s

2. TEMPERATURE FOR SOLDERING IRON
: 280~300°C WITHIN 2s

3. CO-PLANARITY SHALL BE 0.1mm MAX.

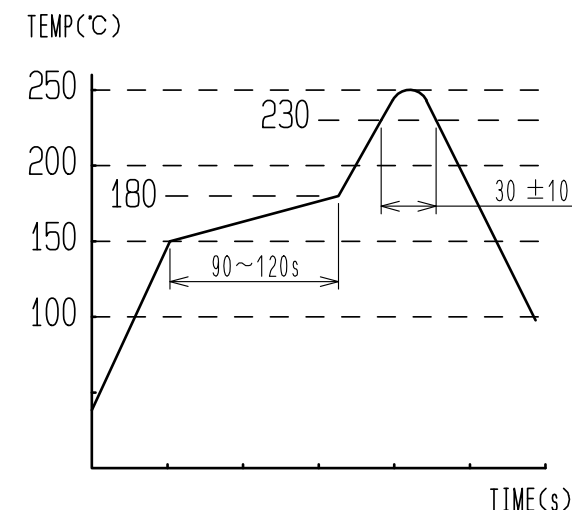
4. RECOMMENDED PCB THICKNESS IS 1.6mm.

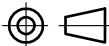
5. RECOMMENDED SOLDER THICKNESS IS 0.10mm.

6. ACCORDING TO THE SOLDERING CONDITIONS, THERE ARE EVENTS WHERE SOLDER DOESN' T GET MOLTEN
DUE TO LOW TEMPERATURE OF SOLDERING AREA.

IN SUCH EVENTS, IF REFLOW TEMPERATURE IS RAISED INTENTIONALLY TO GET THE SOLDER MOLTEN,
IT MAY CAUSE EXCESSIVE HEAT OF UP TO 250°C ON THE OUTER (TOP) SURFACE OF CONNECTOR
THAT CAN LEAD TO THE OCCURRENCE OF BLISTER.

PLEASE ENSURE THAT TEMPERATURE OF OUTER (TOP) SURFACE OF CONNECTOR SHALL NOT EXCEED 250°C WHILE SOLDERING.



3	COPPER ALLOY	SURFACE : TIN PLATING 1μm min		6	POLYESTER					
		UNDER : NICKEL PLATING 1μm min								
2	COPPER ALLOY	SURFACE : TIN PLATING 1μm min		5	POLYSTYRENE					
		UNDER : NICKEL PLATING 1μm min				SURFACE : TIN PLATING 1μm min				
1	PA	GRAY, UL94V-0		4	BRASS	UNDER : NICKEL PLATING 1μm min				
NO.	MATERIAL	FINISH , REMARKS				NO.	MATERIAL	FINISH , REMARKS		
UNITS mm				SCALE 2 : 1		COUNT 2	DESCRIPTION OF REVISIONS DIS-T-00020511	DESIGNED YANG CHUAN XING	CHECKED MH. SHOUJI	DATE 2024032
 HIROSE ELECTRIC CO., LTD.		APPROVED : MH. SHOUJI 20230713				DRAWING NO. EDC-389970-80-00				
		CHECKED : MH. SHOUJI 20230713				PART NO. ZH05-16DS-2H(B)				
		DESIGNED : YANG CHUAN XING 20230713				CODE NO. CL0756-2104-0-80				
		DRAWN : YANG CHUAN XING 20230713				 				

This architectural drawing shows the floor plan of the Temple of Isis at Philae. It features a central rectangular hall with a series of columns, surrounded by a thick wall and an outer enclosure. The drawing is oriented vertically on the page.

Technical drawing of a mechanical part, likely a mold or die, showing a top view. The drawing includes dimensions and a 'PULLING OUT DIRECTION' arrow.

Dimensions and Tolerances:

- Overall width: 44 ± 0.3
- Overall height: 40.4 ± 0.1
- Distance from bottom edge to center of hole: 20.2 ± 0.1
- Distance from left edge to center of hole: 1.75 ± 0.1
- Distance between holes: $P = 24 \pm 0.1$
- Distance between holes (specific): $P = 4 \pm 0.1$
- Distance between holes (specific): 2 ± 0.15
- Radius: $R = 1.5 \pm 0.1$

Other features:

- Section line A-A
- Feature 5 (top right corner)
- Feature 6 (bottom right corner)
- PULLING OUT DIRECTION (indicated by an arrow pointing left)

PRODUCTS DIRECTION

20 EMPTY POCKETS MIN

20 EMPTY POCKETS MIN

φ 1.5 CARRIER HOLES AT FRONT

φ 380

φ 79

(50.4 : WIDTH OF OUTSIDE)

(44.4 : WIDTH OF INSIDE)

IDENTIFICATION TAG

REFERENCE

CARDBOARD DIMENSION (FREE)

A 3D perspective diagram of a rectangular box. The height is labeled H , the depth is labeled D , and the width is labeled W . On the top surface, there is a small square and four parallel lines.

FORM HC0011-5-8 1